

DESCRIPTION

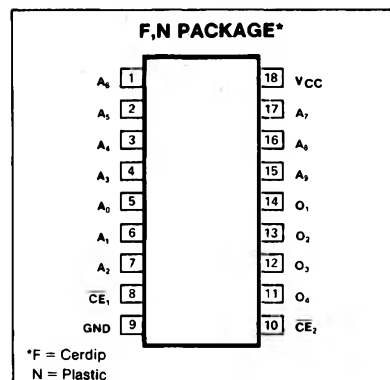
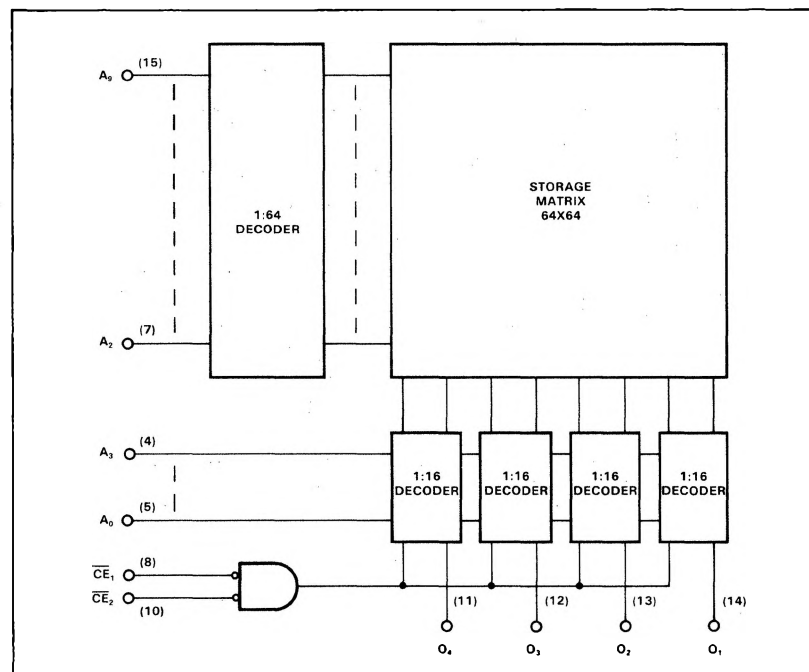
The 82S136 and 82S137 are field programmable, which means that custom patterns are immediately available by following the fusing procedure given in this data sheet. The standard 82S136 and 82S137 are supplied with all outputs at logical low. Outputs are programmed to a logic high level at any specified address by fusing a Ni-Cr link matrix.

These devices include on-chip decoding and 2 chip enable inputs for ease of memory expansion. They feature either open collector or tri-state outputs for optimization of word expansion in bused organizations.

Both 82S136 and 82S137 devices are available in the commercial and military temperature ranges. For the commercial temperature range (0°C to +75°C) specify N82S136/137, F or N, and for the military temperature range (-55°C to +125°C) specify S82S136/137, F.

FEATURES

- **Address access time:**
N82S136/137: 60ns max
S82S136/137: 80ns max
- **Power dissipation:** .13mW/bit typ
- **Input loading:**
N82S136/137: -100 μ A max
S82S136/137: -150 μ A max
- **On-chip address decoding**
- **Output options:**
82S136: Open collector
82S137: Tri-state
- **No separate fusing pins**
- **Unprogrammed outputs are low level**
- **Fully TTL compatible**

PIN CONFIGURATION**BLOCK DIAGRAM****ABSOLUTE MAXIMUM RATINGS**

PARAMETER	RATING	UNIT
V _{CC} Supply voltage	+7	Vdc
V _{IN} Input voltage	+5.5	Vdc
V _{OH} Output voltage		Vdc
V _{OH} High (82S136)	+5.5	
V _O Off-state (82S137)	+5.5	
T _A Temperature range		°C
T _A Operating	0 to +75	
N82S136/137	-55 to +125	
S82S136/137	-65 to +150	
T _{STG} Storage		

DC ELECTRICAL CHARACTERISTICS N82S136/137: $0^{\circ}\text{C} \leq T_A \leq +75^{\circ}\text{C}$, $4.75\text{V} \leq V_{CC} \leq 5.25\text{V}$
 S82S136/137: $-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$, $4.5\text{V} \leq V_{CC} \leq 5.5\text{V}$

PARAMETER	TEST CONDITIONS ¹	N82S136/137			S82S136/137			UNIT
		Min	Typ ²	Max	Min	Typ ²	Max	
V_{IL} Input voltage Low V_{IH} High V_{IC} Clamp	$I_{IN} = -18\text{mA}$	2.0	-0.8	.85 -1.2	2.0	-0.8	.80 -1.2	V
V_{OL} Output voltage Low V_{OH} High (82S137)	$I_{OUT} = 16\text{mA}$ $\overline{CE} = \text{Low}$, $I_{OUT} = -2\text{mA}$, High stored	2.4		0.45	2.4		0.5	V
I_{IL} Input current Low I_{IH} High	$V_{IN} = 0.45\text{V}$ $V_{IN} = 5.5\text{V}$			-100 40			-150 50	μA
I_{OLK} Output current Leakage (82S136) $I_{O(OFF)}$ Off-state (82S137)	$\overline{CE} = \text{High}$, $V_{OUT} = 5.5\text{V}$ $\overline{CE} = \text{High}$, $V_{OUT} = 0.5\text{V}$ $\overline{CE} = \text{High}$, $V_{OUT} = 5.5\text{V}$			40 -40 40			60 -60 60	μA μA
I_{OS} Short circuit (82S137)	$V_{OUT} = 0\text{V}$	-20		-70	-15		-85	mA
I_{CC} V_{CC} supply current			105	140		105	140	mA
C_{IN} Capacitance Input C_{OUT} Output	$V_{CC} = 5.0\text{V}$ $V_{IN} = 2.0\text{V}$ $V_{OUT} = 2.0\text{V}$		5 8			5 8		pF

AC ELECTRICAL CHARACTERISTICS $R_1 = 270\Omega$, $R_2 = 600\Omega$, $C_L = 30\text{pF}$ ¹

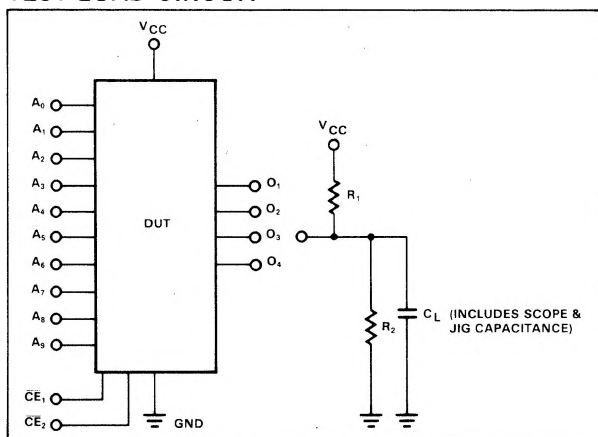
N82S136/137: $0^{\circ}\text{C} \leq T_A \leq +75^{\circ}\text{C}$, $4.75\text{V} \leq V_{CC} \leq 5.25\text{V}$
 S82S136/137: $-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$, $4.5\text{V} \leq V_{CC} \leq 5.5\text{V}$

PARAMETER	TO	FROM	N82S136/137			S82S136/137			UNIT
			Min	Typ ²	Max	Min	Typ ²	Max	
T_{AA} Access time T_{CE}	Output Output	Address Chip enable		40 20	60 30		40 20	80 40	ns
T_{CD} Disable time	Output	Chip disable		20	30		20	40	ns

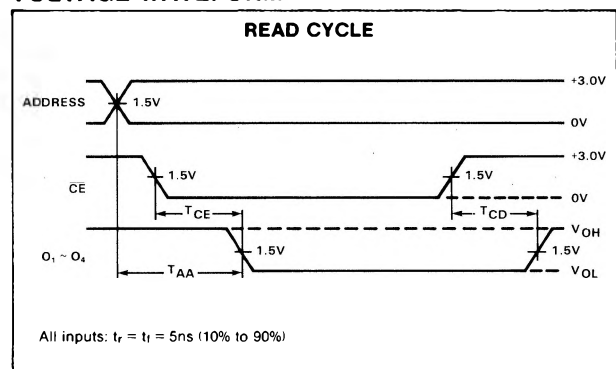
NOTES

- Positive current is defined as into the terminal referenced.
- All typical values are at $V_{CC} = 5\text{V}$, $T_A = 25^{\circ}\text{C}$.

TEST LOAD CIRCUIT



VOLTAGE WAVEFORM



PROGRAMMING SYSTEMS SPECIFICATIONS (Testing of these limits may cause programming of device.) $T_A = +25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	LIMITS			UNIT
		Min	Typ	Max	
V_{CCP} Power supply voltage To program ¹	$I_{CCP} = 375 \pm 75\text{mA}$, Transient or steady state	8.5	8.75	9.0	V
V_{CCH} Verify limit Upper		5.3	5.5	5.7	V
V_{CCL} Lower		4.3	4.5	4.7	
V_S Verify threshold ²		1.4	1.5	1.6	V
I_{CCP} Programming supply current	$V_{CCP} = +8.75 \pm .25\text{V}$	300		450	mA
V_{IH} Input voltage High		2.4		5.5	V
V_{IL} Low		0	0.4	0.8	
I_{IH} Input current High	$V_{IH} = +5.5\text{V}$			50	μA
I_{IL} Low	$V_{IL} = +0.4\text{V}$			-500	
V_{OUT} Output programming voltage ³	$I_{OUT} = 200 \pm 20\text{mA}$, Transient or steady state $V_{OUT} = +17 \pm 1\text{V}$	16.0	17.0	18.0	V
I_{OUT} Output programming current		180	200	220	mA
T_R Output pulse rise time		10		50	μs
t_p CE programming pulse width		0.3	0.4	0.5	ms
t_d Pulse sequence delay		10			μs
T_{PR} Programming time	$V_{CC} = V_{CCP}$			12	sec
T_{PSI} Initial programming pause	$V_{CC} = 0\text{V}$	6			sec
$\frac{T_{PR}}{T_{PR}+T_{PS}}$ Programming duty cycle ⁴				50	%
F_L Fusing attempts per link				2	cycle

NOTES

1. Bypass V_{CC} to GND with a $0.01\mu\text{F}$ capacitor to reduce voltage spikes.
2. V_S is the sensing threshold of the PROM output voltage for a programmed bit. It normally constitutes the reference voltage applied to a comparator circuit to verify a successful fusing attempt.
3. Care should be taken to insure the $17 \pm 1\text{V}$ output voltage is maintained during the entire fusing cycle. The recommended supply is a constant current source clamped at the specified voltage limit.
4. Programming duty cycle is 50% after continuous programming at 100% duty cycle.
5. This is an updated method of programming and does not obsolete any programming systems presently being used.

PROGRAMMING PROCEDURE

1. Terminate all device outputs with a $10\text{K}\Omega$ resistor to V_{CC} . Apply $\overline{CE}_1 = \text{High}$ $\overline{CE}_2 = \text{Low}$.
2. Select the Address to be programmed, and raise V_{CC} to $V_{CCP} = 8.75 \pm .25\text{V}$.
3. After $10\mu\text{s}$ delay, apply $V_{OUT} = +17 \pm 1\text{V}$ to the output to be programmed. Program one output at the time.
4. After $10\mu\text{s}$ delay, pulse the \overline{CE}_1 input to logic low for 0.3 to 0.5ms.
5. After $10\mu\text{s}$ delay, remove $+17\text{V}$ from the programmed output.
6. To verify programming, after $10\mu\text{s}$ delay, lower V_{CC} $V_{CCH} = +5.5 \pm .2\text{V}$, and apply a logic low level to the CE input. The programmed output should remain in the high state. Again, lower V_{CC} to $V_{CCL} = +4.5 \pm .2\text{V}$, and verify that the programmed output remains in the high state.
7. Raise V_{CC} to $V_{CCP} = 8.75 \pm .25\text{V}$, and repeat steps 3 through 6 to program other bits at the same address.
8. After $10\mu\text{s}$ delay, repeat steps 2 through 7 to program all other address locations.

